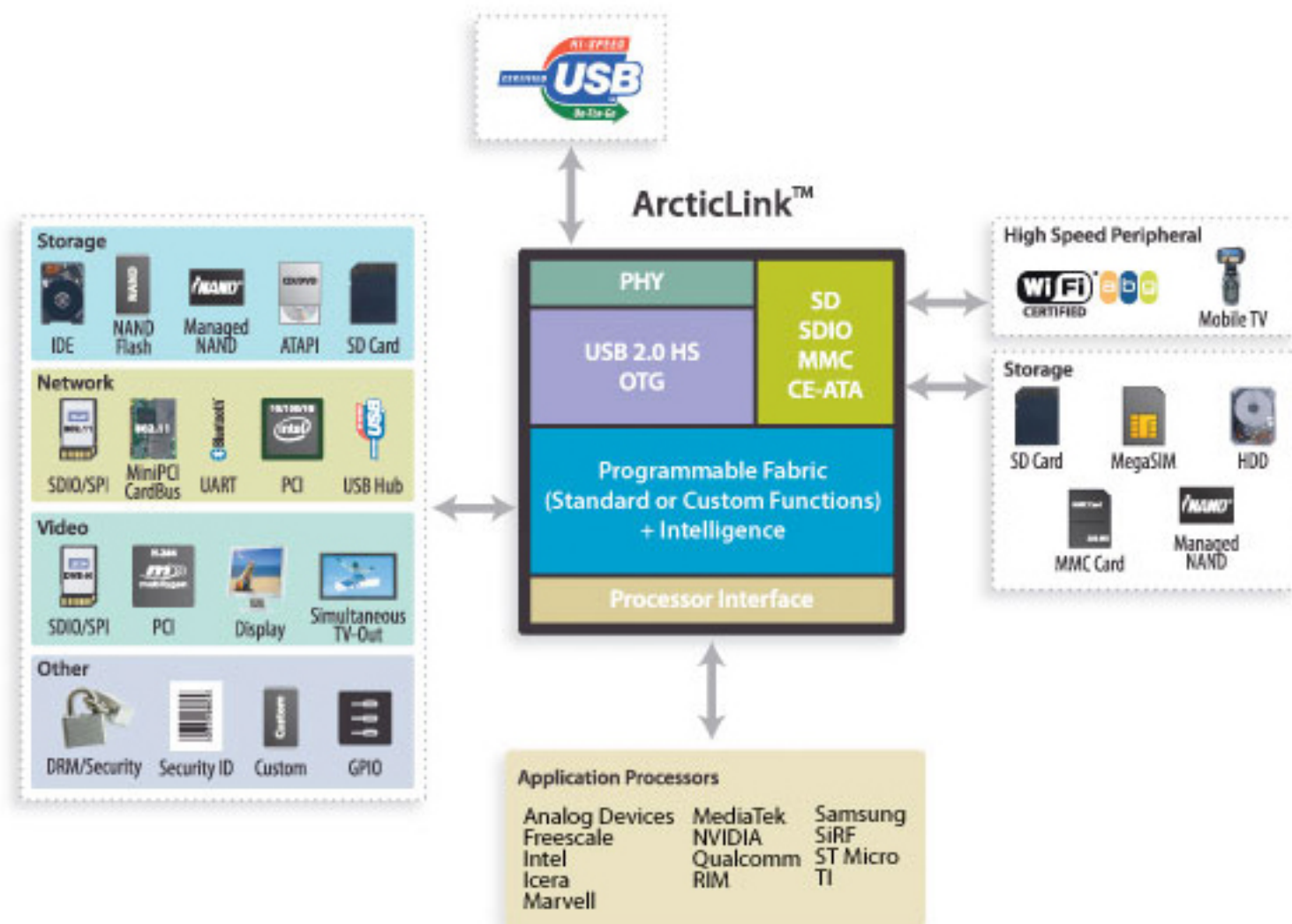


Programmable Connectivity Solution Platform

The Ultra-Low Power, Integrated Programmable Connectivity Platform

- Integrated, single-chip solution for multiple peripheral host controllers and interfaces to reduce both system BOM cost and board space.
- Flexible platform with configurable Hi-Speed USB 2.0 On-The-Go (OTG), high-speed SDIO, multi-format storage solutions and programmable fabric for additional solutions, intelligence, and custom functions.
- Fast time-to-market with complete ultra-low power connectivity solutions.



ArcticLink Architecture

Key Platform Features

The ArcticLink® Solution Platform family of programmable connectivity combines interconnect building blocks, such as Hi-Speed USB 2.0 OTG, SDIO and CE-ATA Host Controllers, with an embedded ultra-low power programmable fabric block, all in a single-chip solution. The combination of small form factor packaging, ultra-low power technology and host bus interface configurability makes this platform ideal for addressing emerging connectivity requirements in power critical portable and mobile consumer electronics applications.

Through the on-chip programmable fabric, the host bus interface can be tailored to expand the peripheral set of a broad variety of common mobile application processor families, to meet the emerging connectivity requirements for wired/wireless communications and media storage. With an innovative internal split bus architecture, the platform enables sustained and concurrent data transfers between slow- and high-speed peripherals, and to/from the common programmable fabric-based host interface.